

This listing of claims will replace all prior versions, and listing, of claims in the application:

**Listing of Claims:**

Claims 1-45 (Previously cancelled)

46. (Previously Amended) A double-sided printed wiring board comprising:

an insulator substrate having at least first and second generally parallel surfaces and a blind via extending from said first surface, the blind via having a sidewall;

a cured mass of a flowable conductive material extending over the first surface and filling said blind via and having an end located adjacent to the first surface of said insulator substrate; and

a conductive pad disposed over the cured mass of flowable conductive material and being in electrical communication with the cured mass of flowable conductive material.

47. (Previously Added) The board according to claim 46, wherein said cured mass of flowable conductive material is selected from the group consisting of conductive inks, conductive pastes, and conductive adhesives.

48. (Previously Added) The board according to claim 46, wherein said conductive pad comprises copper.

49. (Currently Amended) The board according to claim 48, wherein said conductive pad has a thickness greater than ~~approximately~~ 0.2 mils.

50. (Currently Amended) A printed circuit board (PCB) comprising:

a substrate having at least first and second generally parallel surfaces and a blind via extending from said first surface, the blind via having a sidewall;

a first conductive layer extending over ~~substantially all of the~~ first surface and the walls of the blind via, such that said via still maintains an opening, said first conductive

material comprising electrolytically deposited copper having a substantially uniform thickness exceeding approximately 0.2 mils;

a second conductive material disposed in said opening to substantially fill said blind via; and

a third conductive material disposed on said first conductive layer on said first surface, and over the surface of an end portion of said second conductive material in said opening.

51. (Previously Added) The board according to claim 50, wherein said second conductive material is cured flowable conductive material.

52. (Previously Added) The board according to claim 51, wherein said second conductive material is a conductive ink.

53. (Currently Amended) A circuit board comprising:

a substrate having at least first and second generally parallel surfaces and a blind via extending from the first surface, the blind via having a sidewall;

a first conductive layer extending over substantially all of the first surface and the walls of the though-hole via;

a conductive material positioned within and filling the blind via,  
~~the conductive material plugging the blind via such that~~  
~~the blind via has no opening extending from the first~~  
~~surface;~~ and

a second conductive layer extending over substantially all of the first conductive layer on the first surface, and over ~~an end portion of~~ the conductive material positioned within the blind via.

54. (Previously Added) The circuit board of claim 53 wherein the first and second surfaces are exterior surfaces of the substrate.

55. (Previously Added) The circuit board of claim 53 wherein the first conductive layer comprises copper.

56. (Previously Added) The circuit board of claim 55 wherein the second conductive layer comprises copper.

57. (Previously Added) The circuit board of claim 53 wherein the conductive material positioned within the via is selected from the group consisting of conductive inks, conductive pastes, and conductive adhesives.

58. (Previously Added) The circuit board of claim 57 wherein the conductive material is a conductive ink.

59. (Previously Added) The circuit board of claim 58 wherein the conductive ink comprises at least one of silver, copper, and a noble metal.

60. (Previously Added) The circuit board of claim 53 wherein the first and second conductive layers are adapted to be etched to thereby form a conductive pad positioned on the conductive material plugging the via.

61. (New) The circuit board of claims 46, 50, or 53 wherein the blind via is a buried via.

62. (New) The circuit board of claims 46, 50, or 53 wherein the blind via is a through-hole blind via.